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(12) United States Design Patent

Sekimoto

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(54) **SEMICONDUCTOR ELEMENT**

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(73) Assignee: **Sony Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/130,540**

(22) Filed: **Oct. 4, 2000**

(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 174/524, 174/525; 257/690; 361/752, 798, 820

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(74) *Attorney, Agent, or Firm*—Rader,Fishman & Grauer

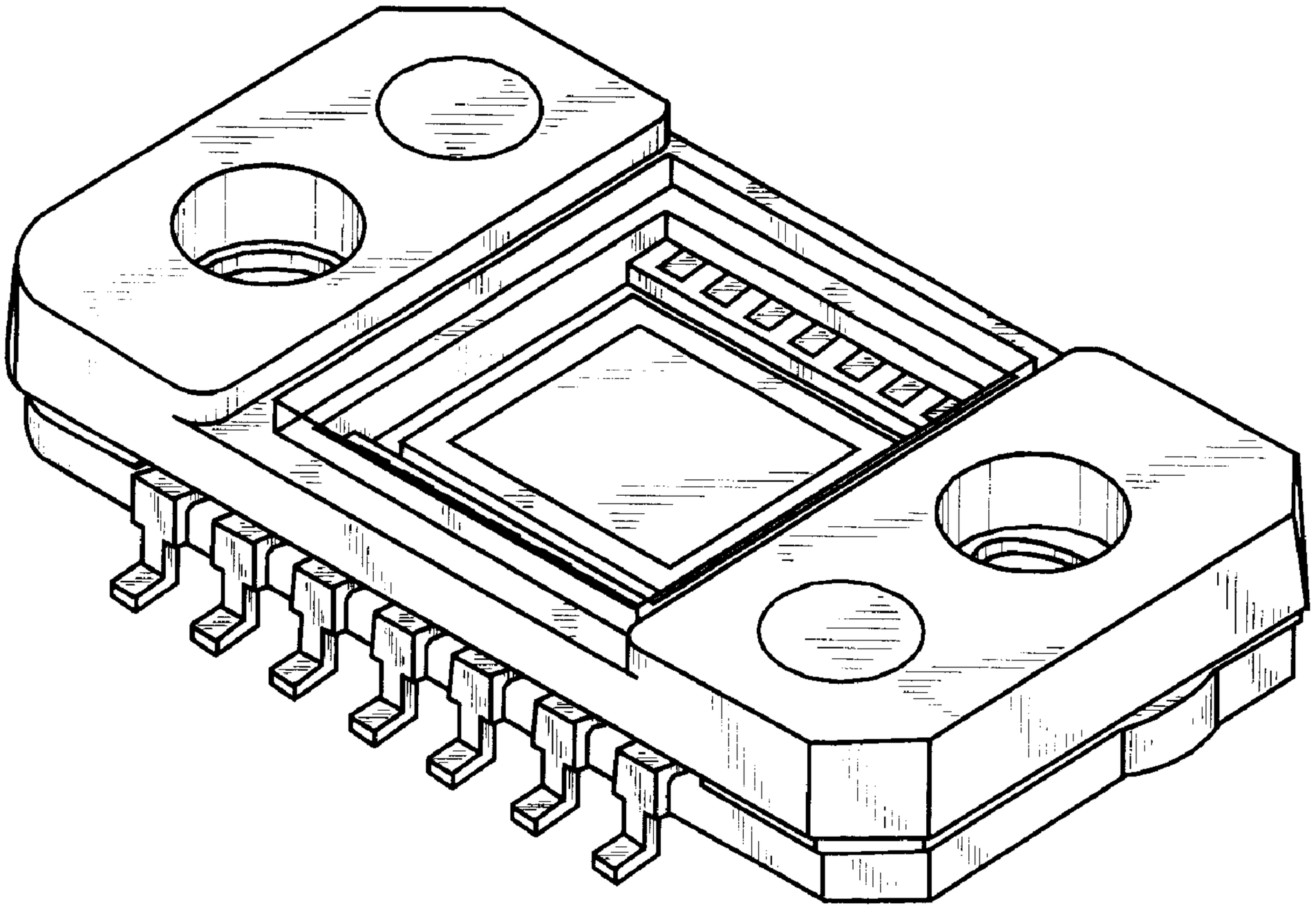
(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. **1** is a top, front perspective view of a semiconductor element showing my new design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a bottom plan view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a front elevational view thereof; and,
FIG. **7** is a rear elevational view thereof.

1 Claim, 4 Drawing Sheets



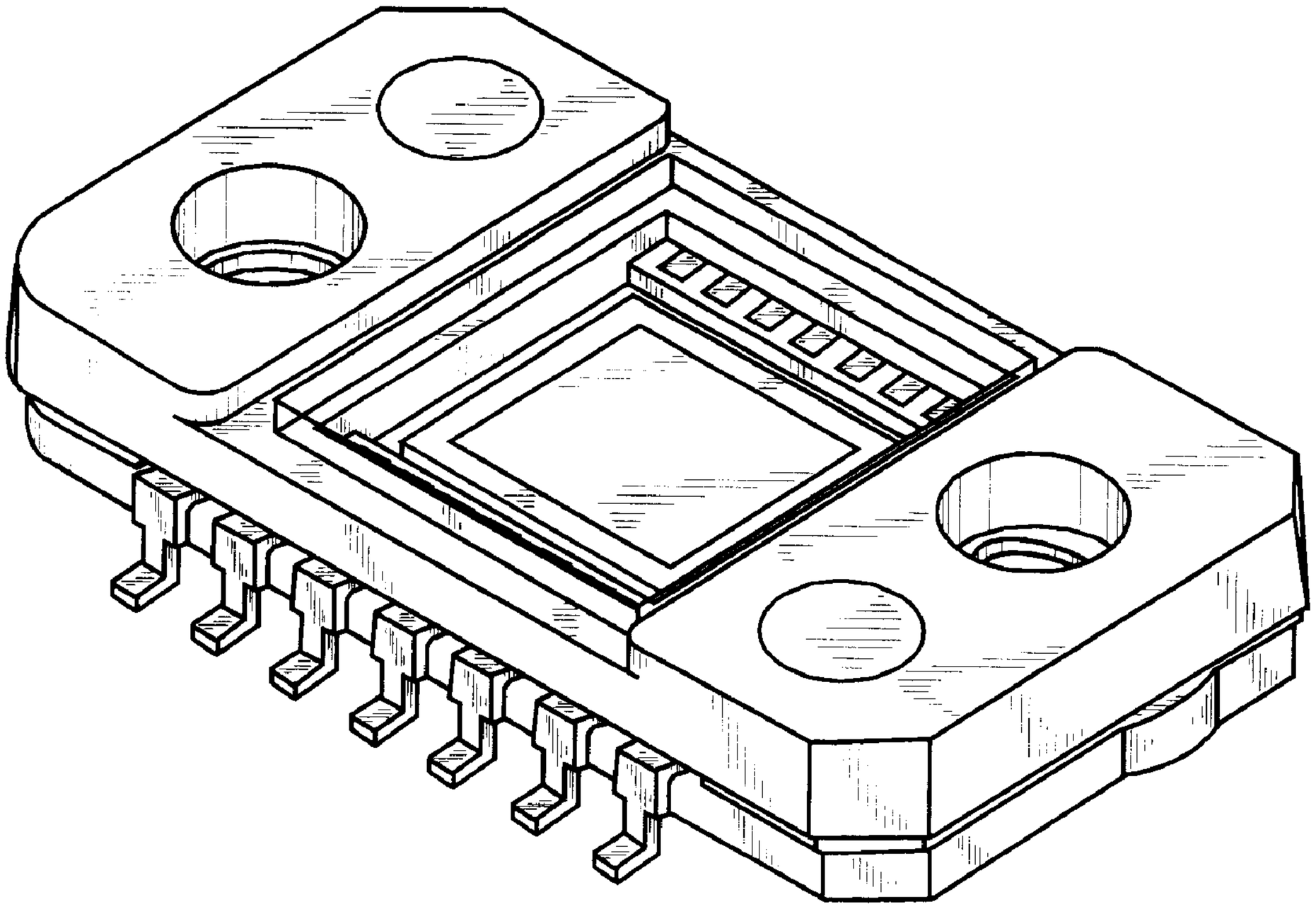


Fig. 1

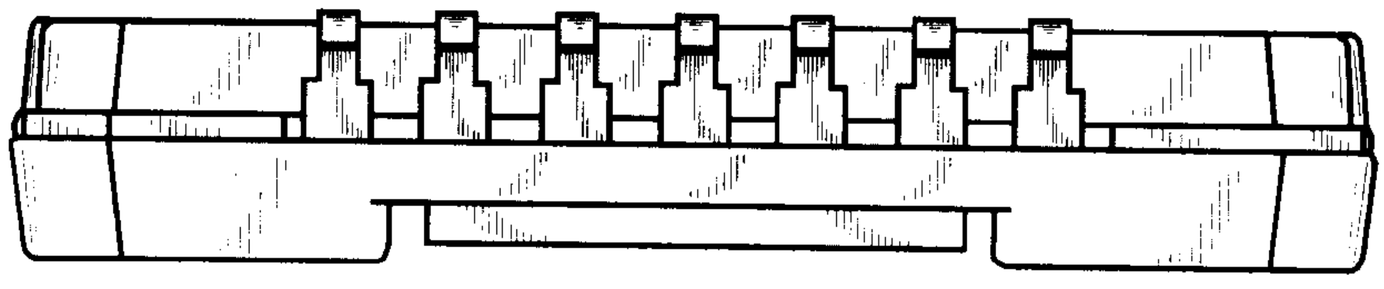


Fig. 2

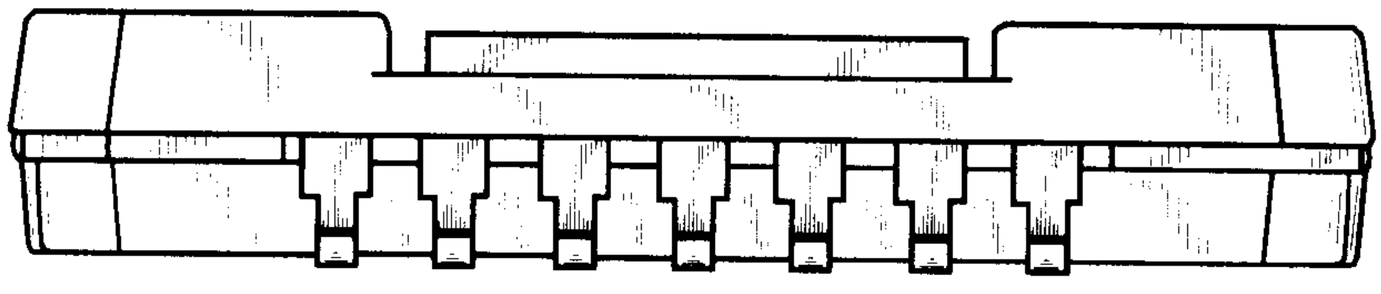


Fig. 3

Fig. 4

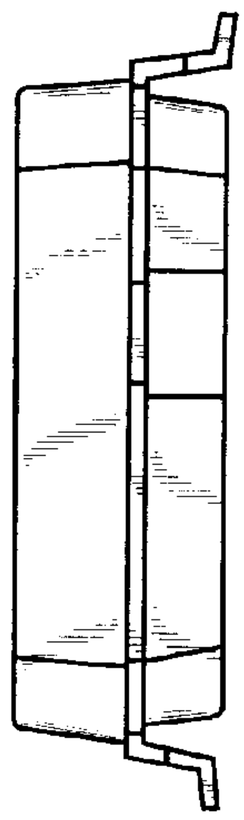


Fig. 5

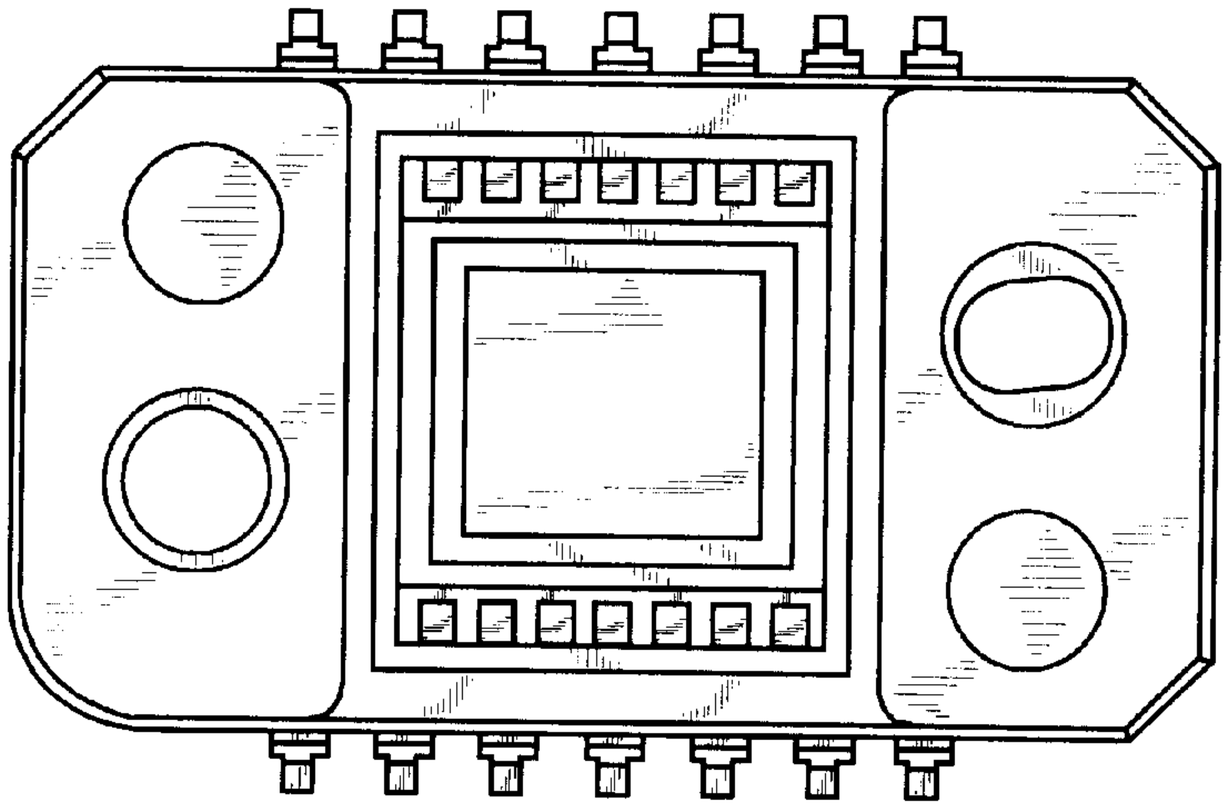


Fig. 6

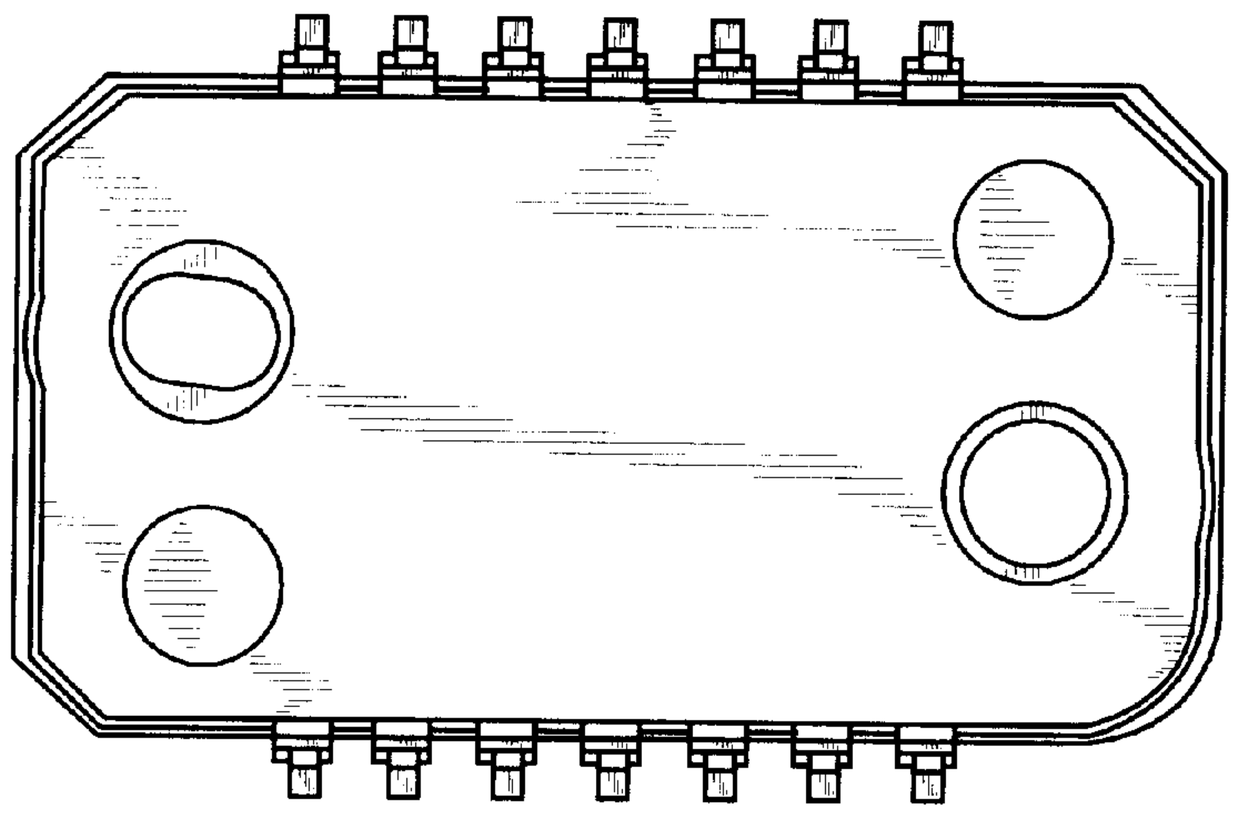


Fig. 7